Claims

[c1] 1. An optical-disk stamper comprising:

a stamper body;

a molding surface formed on a side of said stamper body and furnished with bumps for transfer-forming pits onto an optical disk; wherein

at least said molding surface, including said bumps, is formed of a synthetic polymer whose the diffusivityrmal is 0.01 m^2 /h or less.

[c2] 2. An optical-disk stamper as set forth in claim 1, wherein the entire stamper body is formed from a synthetic polymer whose thermal diffusivity is 0.01 m^2 /h or less, superficially on which said molding surface furnished with said bumps is formed.

[c3] 3. An optical-disk stamper, comprising:

a stamper body formed from a metal baseplate;

a molding layer laminated onto one side of said stamper body, said molding layer being formed from a synthetic polymer whose thermal diffusivity is 0.01 m^2 /h or less; and

bumps furnished superficially on said molding layer to form an optical-disk molding surface.

[c4] 4. An optical-disk stamper, comprising:

a stamper body formed from a metal baseplate;

a molding surface furnished with bumps, formed one side of said stamper body; and

a synthetic-polymer coating layer whose thermal diffusivity is 0.01 m^2 /h or less, coated on sid molding surface, including said bumps.

[c5] 5. An optical-disk stamper as set forth in claim 1, wherein said synthetic polymer is made up of heat-hardening resins including a phenolic or an epoxy resin whose therdiffusivity mal is from 0.0004 to 0.001 m^2 /h.

[c6] 6. An optical-disk stamper as set forth in claim 2, wherein said synthetic polymer is made up of heat-hardening resins including a phenolic or an epoxy resin whose therdiffusivity mal is from 0.0004 to 0.001 m^2 /h.

[c7] 7. An optical-disk stamper as set forth in claim 3, wherein said synthetic polymer is made up of heat-hardening resins including a phenolic or an epoxy resin whose therdiffusivity mal is from 0.0004 to 0.001 m^2/h.

[c8] 8. An optical-disk stamper as set forth in claim 4, wherein said synthetic-polymer coating layer is made up of heat-hardening resins including a phenolic or an epoxy resin whose therdiffusivity mal is from 0.0004 to 0.001 m^2/h.